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Date

April 16, 2009

TO

Director, Office of Data Management

FROM

: Office of Petitions

SUBJECT

Withdrawal from Issue of Application No. 10/591,455

Applicant(s)

: Hideo Aoki, et al.

Application No. : 10/591,455

Filed

: September 1, 2006

The above-identified application has been assigned Patent No. 7,528,193 and an issue date of May 5, 2009.

It is hereby directed that this application be withdrawn from issue at the request of the applicant. Do not refund the issue fee.

The following erratum should be published in the Official Gazette if the above-identified application is published in the OG of May 5, 2009:

"All reference to Patent No. 7,528,193 to Hideo Aoki, et al. of Japan for THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME appearing in the Official Gazette of May 5, 2009 should be deleted since no patent was granted."

/WMA/ April M. Wise Petitions Examiner Office of Petitions

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